Holo/Or DeepCleave Glass Cutting with Fluence Laser



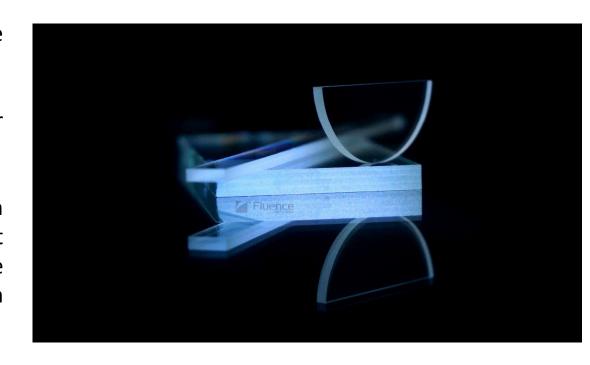






DeepCleave

- Dedicated module for enhancing the laser glass cutting process
- Yielding higher throughput and a finer cutting process
- The DeepCleave module focuses an incident single mode laser into a tight spot with ~1.8um waist size along the entire Depth of Focus range (1-2mm typical range).

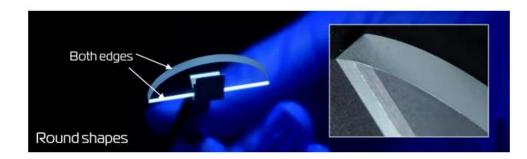


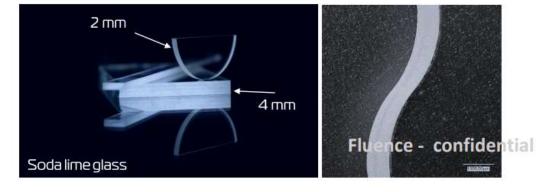


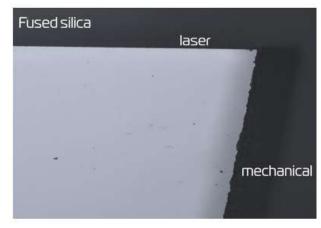


Glass Cutting with Elongated Focus

Examples of glass cutting with femtosecond fiber laser and DeepCleave module







Done with:

- √ Jasper20 by Fluence
- ✓ DeepCleave by Holo/Or





System Setup

Simple Setup – Easy to Integrate

Jasper 20 laser by Fluence

Average power: 20W

• Wavelength: 1030nm

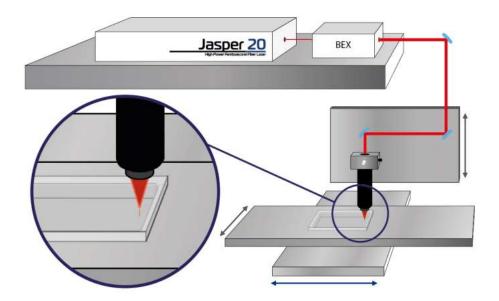
• M2<1.3

- <250 fs up to 8 ps
- <100 μJ (200 μJ in a burst)
- Single pulse to 20 MHz

• Holo/Or DeepCleave

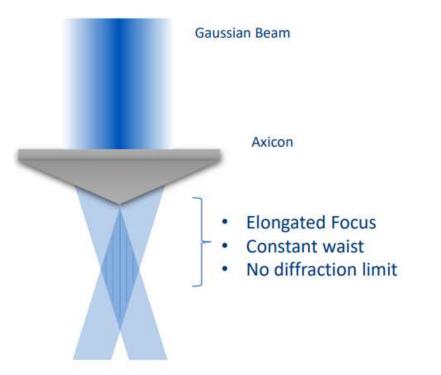
- The focused spot is equivalent to 0.35 objective NA
- 1.8 um beam diameter
- 7.4 mm working distance (larger available)
- Focus length: 1.0 mm in air (other values are available)
- Flat-top distribution along the focus

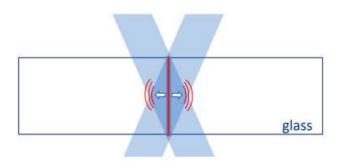






Bessel Beam Glass Processing





Requirements:

- ☐ Sufficient fluence within focal volume ~1kJ/cm³
- ☐ Ultrashort pulse (high intensity)
- Appropriate ratio of cone angle to pulse peak intensity to reduce nonlinear propagation due to electron avalanche

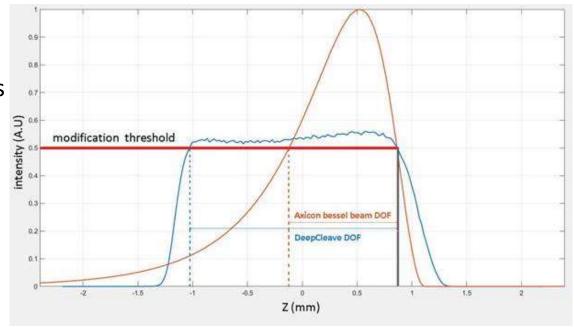
Mishchik, K., et al. *Optics Express* 25.26 (2017). Courvoisier, François, et al. Applied Physics A 112.1 (2013): 29-34 Hendricks, F., et al. *Frontiers in Ultrafast Optics: Biomedical, Scientific, and Industrial Applications XVI*. Vol. 9740 SPIE, 2016.





DeepCleave Advantages over the Axicon Bessel Beam

- Constant peak power along the focus region
- Cuts twice the thickness
- Double the throughput and savings on energy







Cutting Speed

- 0.75-1.0 m/s for 1.1 mm BK7
- 0.19-0.205 m/s for 4.0 mm soda lime glass
- Cutting in any direction, proper separation, high edge quality







More Glass Cutting Results

